

74LCX16245

Low Voltage 16-Bit Bidirectional Transceiver with 5V Tolerant Inputs and Outputs

General Description

The LCX16245 contains sixteen non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus oriented applications. The device is designed for low voltage (2.5V or 3.3V) V_{CC} applications with capability of interfacing to a 5V signal environment. The device is byte controlled. Each byte has separate control inputs which could be shorted together for full 16-bit operation. The T/\bar{R} inputs determine the direction of data flow through the device. The \overline{OE} inputs disable both the A and B ports by placing them in a high impedance state.

The LCX16245 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 5V tolerant inputs and outputs
- 2.3V–3.6V V_{CC} specifications provided
- 4.5 ns t_{PD} max ($V_{CC} = 3.3V$), 20 μA I_{CC} max
- Power down high impedance inputs and outputs
- Supports live insertion/withdrawal (Note 1)
- ± 24 mA output drive ($V_{CC} = 3.0V$)
- Uses patented noise/EMI reduction circuitry
- Latch-up performance exceeds 500 mA
- ESD performance:
 - Human body model > 2000V
 - Machine model > 200V
- Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

Note 1: To ensure the high-impedance state during power up or down, \overline{OE} should be tied to V_{CC} through a pull-up resistor; the minimum value or the resistor is determined by the current-sourcing capability of the driver.

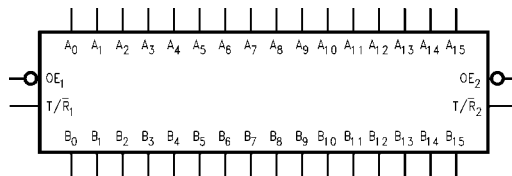
Ordering Code:

| Order Number | Package Number | Package Description |
|---------------------------------|----------------|---|
| 74LCX16245G (Note 2)(Note 3) | BGA54A | 54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide |
| 74LCX16245MEA (Note 3) | MS48A | 48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide |
| 74LCX16245MTD (Note 3) | MTD48 | 48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide |

Note 2: Ordering code "G" indicates Trays.

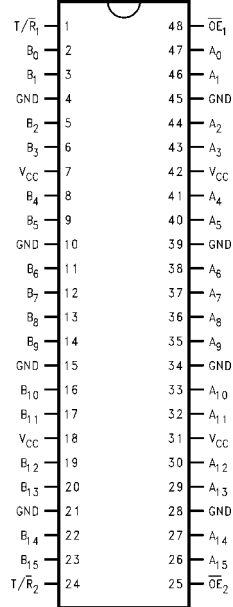
Note 3: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol

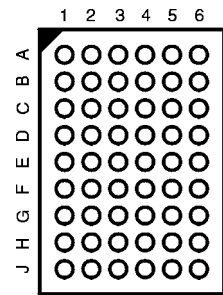


Connection Diagrams

Pin Assignment for SSOP and TSSOP



Pin Assignment for FBGA



(Top Thru View)

Pin Descriptions

| Pin Names | Description |
|-------------------|----------------------------------|
| \overline{OE}_n | Output Enable Input |
| T/R_n | Transmit/Receive Input |
| A_0 – A_{15} | Side A Inputs or 3-STATE Outputs |
| B_0 – B_{15} | Side B Inputs or 3-STATE Outputs |
| NC | No Connect |

FBGA Pin Assignments

| | 1 | 2 | 3 | 4 | 5 | 6 |
|----------|----------|----------|----------|-------------------|----------|----------|
| A | B_0 | NC | T/R_1 | \overline{OE}_1 | NC | A_0 |
| B | B_2 | B_1 | NC | NC | A_1 | A_2 |
| C | B_4 | B_3 | V_{CC} | V_{CC} | A_3 | A_4 |
| D | B_6 | B_5 | GND | GND | A_5 | A_6 |
| E | B_8 | B_7 | GND | GND | A_7 | A_8 |
| F | B_{10} | B_9 | GND | GND | A_9 | A_{10} |
| G | B_{12} | B_{11} | V_{CC} | V_{CC} | A_{11} | A_{12} |
| H | B_{14} | B_{13} | NC | NC | A_{13} | A_{14} |
| J | B_{15} | NC | T/R_2 | OE_2 | NC | A_{15} |

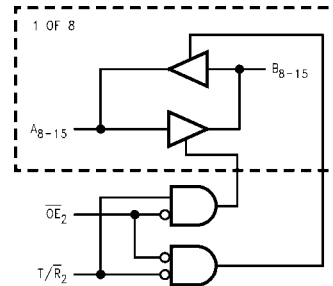
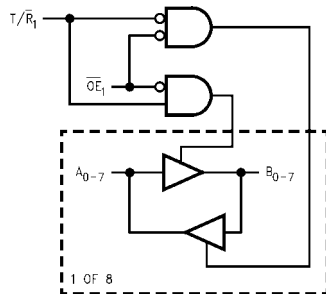
Truth Tables

| Inputs | | Outputs |
|-------------------|---------|---|
| \overline{OE}_1 | T/R_1 | |
| L | L | Bus B_0 – B_7 Data to Bus A_0 – A_7 |
| L | H | Bus A_0 – A_7 Data to Bus B_0 – B_7 |
| H | X | HIGH Z State on A_0 – A_7 , B_0 – B_7 |

| Inputs | | Outputs |
|-------------------|---------|---|
| \overline{OE}_2 | T/R_2 | |
| L | L | Bus B_8 – B_{15} Data to Bus A_8 – A_{15} |
| L | H | Bus A_8 – A_{15} Data to Bus B_8 – B_{15} |
| H | X | HIGH Z State on A_8 – A_{15} , B_8 – B_{15} |

H = HIGH Voltage Level
 L = LOW Voltage Level
 X = Immaterial
 Z = High Impedance

Logic Diagrams



Note: Please note that these diagrams are provided only for the understanding of logic operations and should not be used to estimate propagation delays.

| Absolute Maximum Ratings ^(Note 4) | | | | | | |
|---|--|--|---|---------------------------------|------|-------|
| Symbol | Parameter | Value | Conditions | Units | | |
| V _{CC} | Supply Voltage | -0.5 to +7.0 | | V | | |
| V _I | DC Input Voltage | -0.5 to +7.0 | | V | | |
| V _O | DC Output Voltage | -0.5 to +7.0 -0.5 to V _{CC} + 0.5 | Output in 3-STATE Output in HIGH or LOW State (Note 5) | V | | |
| I _{IK} | DC Input Diode Current | -50 | V _I < GND | mA | | |
| I _{OK} | DC Output Diode Current | -50 +50 | V _O < GND V _O > V _{CC} | mA | | |
| I _O | DC Output Source/Sink Current | ±50 | | mA | | |
| I _{CC} | DC Supply Current per Supply Pin | ±100 | | mA | | |
| I _{GND} | DC Ground Current per Ground Pin | ±100 | | mA | | |
| T _{STG} | Storage Temperature | -65 to +150 | | °C | | |
| Recommended Operating Conditions (Note 6) | | | | | | |
| Symbol | Parameter | Min | Max | Units | | |
| V _{CC} | Supply Voltage | Operating | 2.0 | 3.6 | V | |
| | | Data Retention | 1.5 | 3.6 | | |
| V _I | Input Voltage | 0 | 5.5 | V | | |
| V _O | Output Voltage | HIGH or LOW State | 0 | V _{CC} | V | |
| | | 3-STATE | 0 | 5.5 | | |
| I _{OH} /I _{OL} | Output Current | V _{CC} = 3.0V – 3.6V | | ±24 | mA | |
| | | V _{CC} = 2.7V – 3.0V | | ±12 | | |
| | | V _{CC} = 2.3V – 2.7V | | ±8 | | |
| T _A | Free-Air Operating Temperature | -40 | 85 | °C | | |
| Δt/ΔV | Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V | 0 | 10 | ns/V | | |
| <p>Note 4: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.</p> <p>Note 5: I_O Absolute Maximum Rating must be observed.</p> <p>Note 6: Unused inputs or I/O's must be held HIGH or LOW. They may not float.</p> | | | | | | |
| DC Electrical Characteristics | | | | | | |
| Symbol | Parameter | Conditions | V _{CC} (V) | T _A = -40°C to +85°C | | Units |
| | | | | Min | Max | |
| V _{IH} | HIGH Level Input Voltage | | 2.3 – 2.7 | 1.7 | | V |
| | | | 2.7 – 3.6 | 2.0 | | |
| V _{IL} | LOW Level Input Voltage | | 2.3 – 2.7 | | 0.7 | V |
| | | | 2.7 – 3.6 | | 0.8 | |
| V _{OH} | HIGH Level Output Voltage | I _{OH} = -100 μA | 2.3 – 3.6 | V _{CC} - 0.2 | | V |
| | | I _{OH} = -8 mA | 2.3 | 1.8 | | |
| | | I _{OH} = -12 mA | 2.7 | 2.2 | | |
| | | I _{OH} = -18 mA | 3.0 | 2.4 | | |
| | | I _{OH} = -24 mA | 3.0 | 2.2 | | |
| V _{OL} | LOW Level Output Voltage | I _{OL} = 100 μA | 2.3 – 3.6 | | 0.2 | V |
| | | I _{OL} = 8mA | 2.3 | | 0.6 | |
| | | I _{OL} = 12 mA | 2.7 | | 0.4 | |
| | | I _{OL} = 16 mA | 3.0 | | 0.4 | |
| | | I _{OL} = 24 mA | 3.0 | | 0.55 | |
| I _I | Input Leakage Current | 0 ≤ V _I ≤ 5.5V | 2.3 – 3.6 | | ±5.0 | μA |
| I _{OZ} | 3-STATE I/O Leakage | 0 ≤ V _O ≤ 5.5V V _I = V _{IH} or V _{IL} | 2.3 – 3.6 | | ±5.0 | μA |
| I _{OFF} | Power-Off Leakage Current | V _I or V _O = 5.5V | 0 | | 10 | μA |

| DC Electrical Characteristics (Continued) | | | | | | | | |
|---|--|---|------------------------|---------------------------------|-------|-------------------------------|-----|-------|
| Symbol | Parameter | Conditions | V _{CC} (V) | T _A = -40°C to +85°C | | Units | | |
| | | | | Min | Max | | | |
| I _{CC} | Quiescent Supply Current | V _I = V _{CC} or GND | 2.3–3.6 | | 20 | μA | | |
| | | 3.6V ≤ V _I , V _O ≤ 5.5V (Note 7) | 2.3–3.6 | | ±20 | | | |
| ΔI _{CC} | Increase in I _{CC} per Input | V _{IH} = V _{CC} - 0.6V | 2.3–3.6 | | 500 | μA | | |
| Note 7: Outputs disabled or 3-STATE only. | | | | | | | | |
| AC Electrical Characteristics | | | | | | | | |
| Symbol | Parameter | T _A = -40°C to +85°C, R _L = 500Ω | | | | | | Units |
| | | V _{CC} = 3.3V ± 0.3V | | V _{CC} = 2.7V | | V _{CC} = 2.5V ± 0.2V | | |
| | | C _L = 50 pF | | C _L = 50 pF | | C _L = 30 pF | | |
| | | Min | Max | Min | Max | Min | Max | |
| t _{PHL} | Propagation Delay | 1.5 | 4.5 | 1.5 | 5.2 | 1.5 | 5.4 | ns |
| t _{PLH} | A _n to B _n or B _n to A _n | 1.5 | 4.5 | 1.5 | 5.2 | 1.5 | 5.4 | |
| t _{PZL} | Output Enable Time | 1.5 | 6.5 | 1.5 | 7.2 | 1.5 | 8.5 | ns |
| t _{PZH} | | 1.5 | 6.5 | 1.5 | 7.2 | 1.5 | 8.5 | |
| t _{PLZ} | Output Disable Time | 1.5 | 6.4 | 1.5 | 6.9 | 1.5 | 7.7 | ns |
| t _{PHZ} | | 1.5 | 6.4 | 1.5 | 6.9 | 1.5 | 7.7 | |
| t _{OSSL} | Output to Output Skew (Note 8) | | 1.0 | | | | | ns |
| t _{OSLH} | | | 1.0 | | | | | |
| Note 8: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t _{OSSL}) or LOW-to-HIGH (t _{OSLH}). Parameter guaranteed by design. | | | | | | | | |
| Dynamic Switching Characteristics | | | | | | | | |
| Symbol | Parameter | Conditions | V _{CC} (V) | T _A = 25°C | Units | | | |
| | | | | Typical | | | | |
| V _{OLP} | Quiet Output Dynamic Peak V _{OL} | C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V | 3.3 | 0.8 | V | | | |
| | | C _L = 30 pF, V _{IH} = 2.5V, V _{IL} = 0V | 2.5 | 0.6 | | | | |
| V _{OLV} | Quiet Output Dynamic Valley V _{OL} | C _L = 50 pF, V _{IH} = 3.3V, V _{IL} = 0V | 3.3 | -0.8 | V | | | |
| | | C _L = 30 pF, V _{IH} = 2.5V, V _{IL} = 0V | 2.5 | -0.6 | | | | |
| Capacitance | | | | | | | | |
| Symbol | Parameter | Conditions | Typical | Units | | | | |
| C _{IN} | Input Capacitance | V _{CC} = Open, V _I = 0V or V _{CC} | 7 | pF | | | | |
| C _{I/O} | Input/Output Capacitance | V _{CC} = 3.3V, V _I = 0V or V _{CC} | 8 | pF | | | | |
| C _{PD} | Power Dissipation Capacitance | V _{CC} = 3.3V, V _I = 0V or V _{CC} , f = 10 MHz | 20 | pF | | | | |

AC LOADING and WAVEFORMS Generic for LCX Family

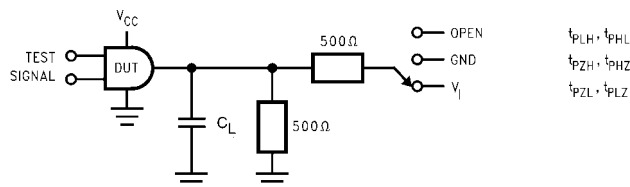
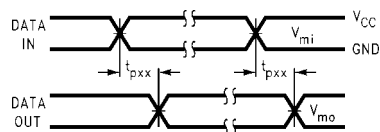
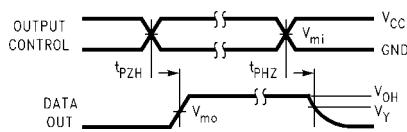


FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)

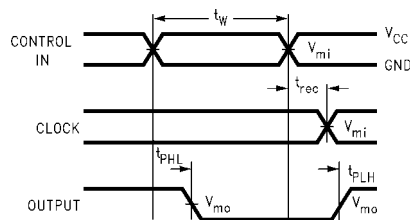
| Test | Switch |
|--------------------|---|
| t_{PLH}, t_{PHL} | Open |
| t_{PZL}, t_{PLZ} | 6V at $V_{CC} = 3.3 \pm 0.3V$ $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$ |
| t_{PZH}, t_{PHZ} | GND |



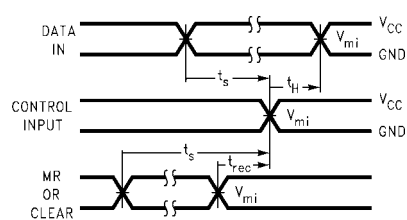
Waveform for Inverting and Non-Inverting Functions



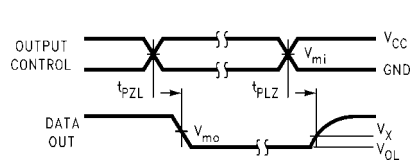
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay, Pulse Width and t_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

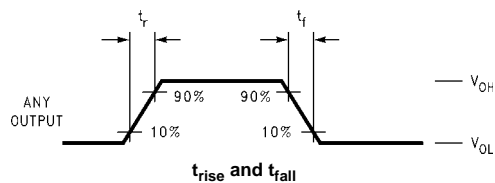
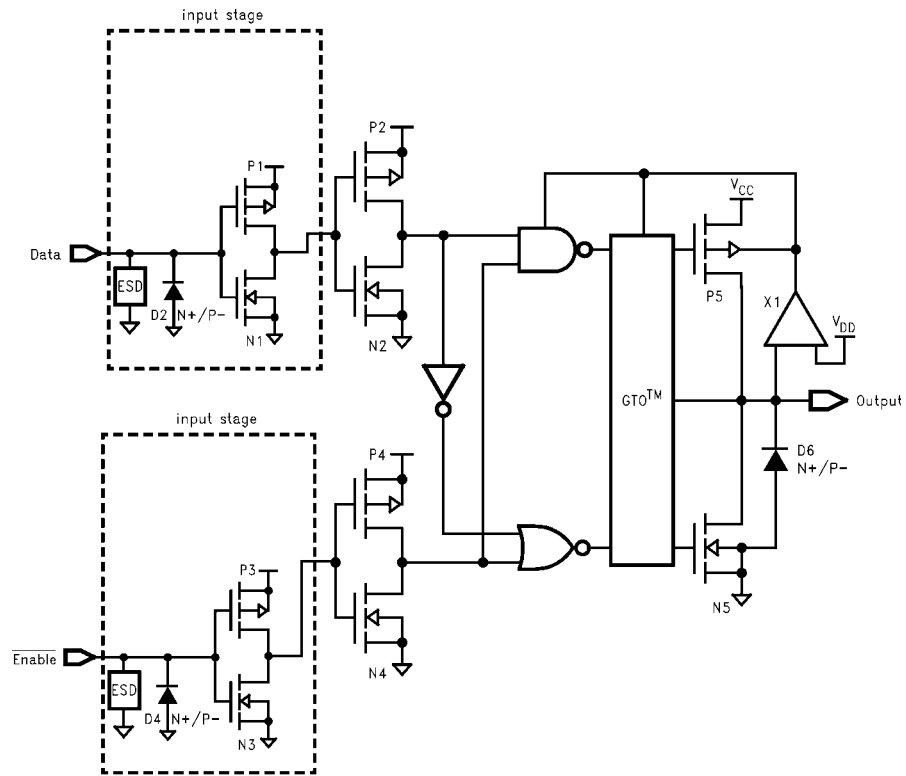


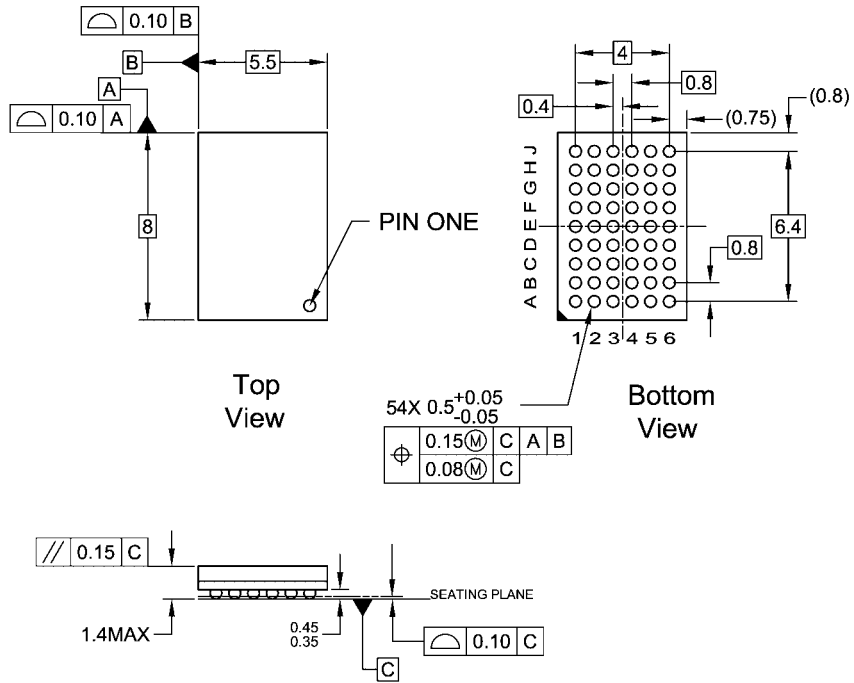
FIGURE 2. Waveforms
(Input Characteristics; $f = 1MHz, t_r = t_f = 3ns$)

| Symbol | V_{CC} | | |
|----------|-----------------|-----------------|------------------|
| | $3.3V \pm 0.3V$ | $2.7V$ | $2.5V \pm 0.2V$ |
| V_{mi} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_{mo} | 1.5V | 1.5V | $V_{CC}/2$ |
| V_x | $V_{OL} + 0.3V$ | $V_{OL} + 0.3V$ | $V_{OL} + 0.15V$ |
| V_y | $V_{OH} - 0.3V$ | $V_{OH} - 0.3V$ | $V_{OH} - 0.15V$ |

Schematic Diagram Generic for LCX Family



Physical Dimensions inches (millimeters) unless otherwise noted



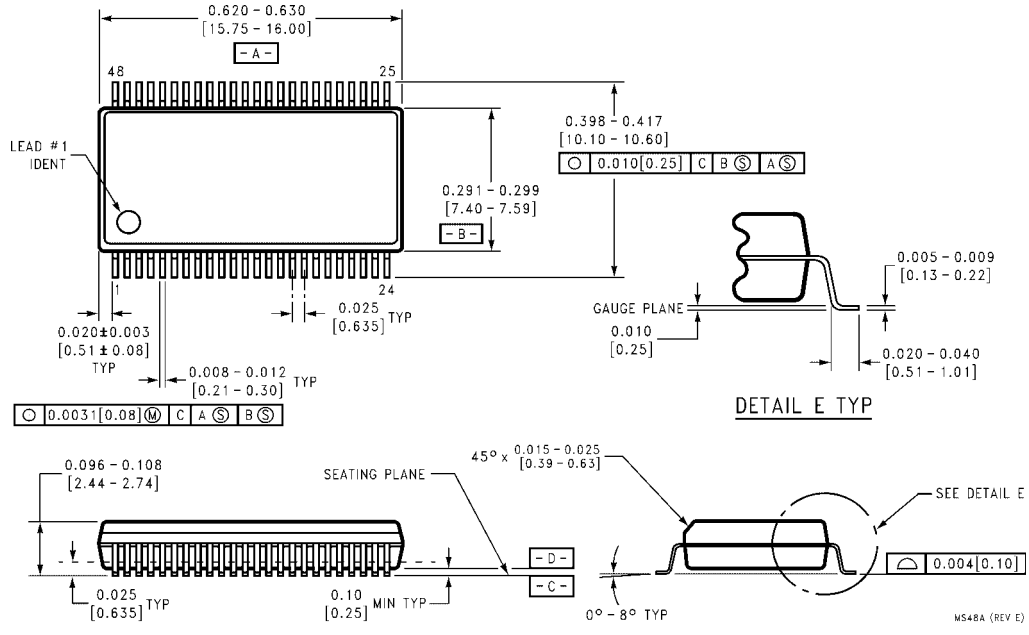
NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- B. ALL DIMENSIONS IN MILLIMETERS
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
.35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
- D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

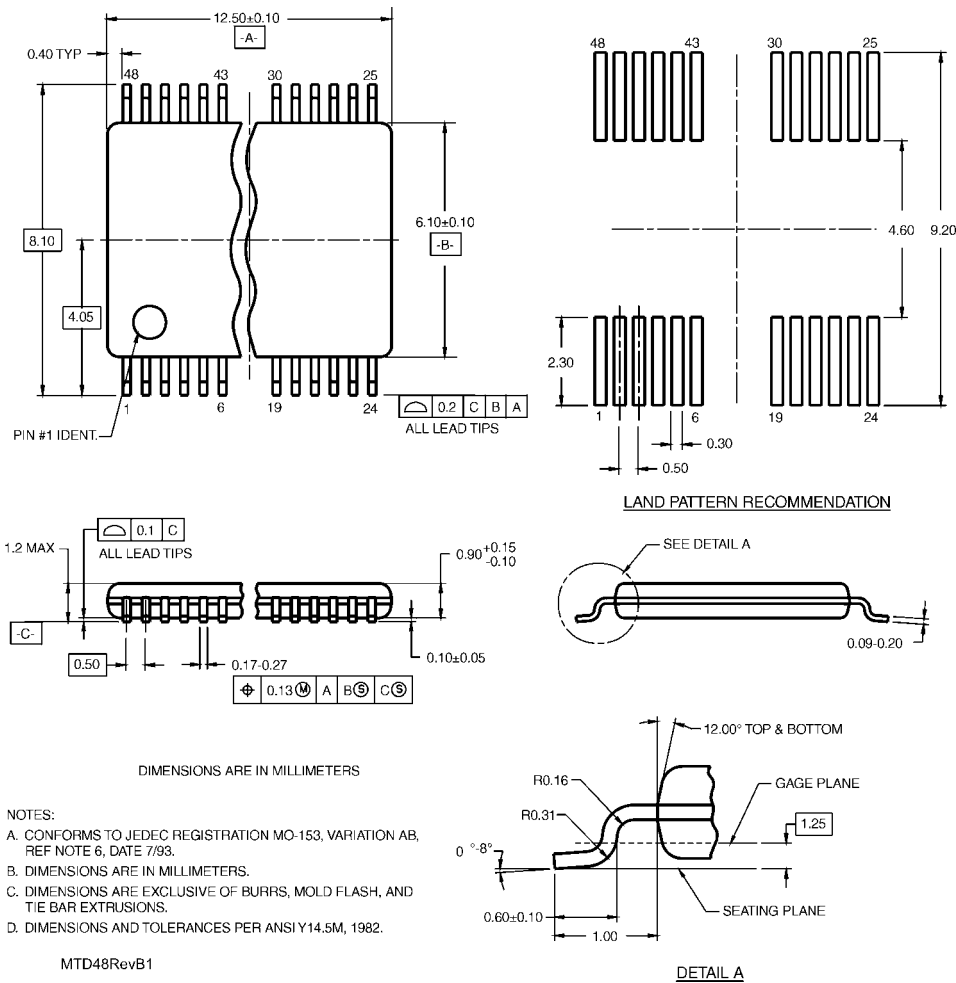
**54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC M0-205, 5.5mm Wide
Package Number BGA54A**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



**48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
Package Number MS48A**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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